

Wiring, Printed - Component

COMPANY

KSG GmbH

AUERBACHER STR 3-5

GORNSDORF, Sachsen 09390 Germany

E143060

Type	Cond Width		Cond Thk	SS/DSO	Area Diam	Max Report date After	Surface Mount	Assembly		Max			Meets UL796	C	
	Min	Edge						Solder Process	Solder Process	Solder Limits	Oper Temp	Flame			
	mm	mm	mic	mm	mm	2022-01-01	Technology	Temp °C	Cycles	°C	sec	°C	Class	DSR	I
Multilayer (Mass-laminated) printed wiring boards															
MLM	0.15	0.15	30.5	DS	91.4	No	-	-	-	250	8	100	V-0	-	-
Multilayer printed wiring boards															
4L	0.04	0.06	9 Int:105	DS	50.8	No	-	-	-	288	20	130	V-1	All	*
4M	0.04	0.06	9 Int:105	DS	50.8	No	-	-	-	288	20	130	V-0	All	*
H2 @	0.039	0.117	64 Int:95	DS	25.4	No	-	-	-	288	10	130	V-0	All	3
M2	0.064	0.10	9 Int:107	DS	50.0	No	-	-	-	288	20	130	V-0	All	*
M3 (ASP 1)	0.04	0.06	5 Int:105	DS	90.0	Yes	Yes	260	6	-	-	130	V-0	All	*
M4	0.064	0.10	9 Int:107	DS	127.0	No	-	-	-	288	20	130	V-0	All	3
M6 (ASP 1)	0.04	0.06	5 Int:70	DS	50.8	No	Yes	260	6	-	-	130	V-0	All	3
M7 (ASP 1)	0.04	0.06	5 Int:105	DS	90.0	Yes	Yes	260	4	-	-	120	V-0	All	3
M8	0.075	0.10	17 Int:35	DS	50.0	No	-	-	-	288	20	130	V-0	All	*

ML	0.064	0.19	18 Int:107	DS	90.2	No	-	-	-	270	8	125	V-0	All	*
ML1	0.064	0.10	9 Int:107	DS	127.0	No	-	-	-	288	20	125	V-0	All	*
ML2	1.100	1.500	30 Int:18	DS	89.9	No	-	-	-	255	8	125	V-0	All	*
ML3	1.350	1.700	30 Int:400	DS	90	No	-	-	-	230	3	130	V-0	All	*
ML4	0.064	0.100	9 Int:107	DS	127.0	No	-	-	-	288	20	130	V-0	All	3
ML5	0.064	0.10	9 Int:102	DS	127.0	No	-	-	-	288	20	130	V-0	All	*
ML6	0.064	0.190	18 Int:107	DS	90.2	No	-	-	-	270	8	130	V-0	All	*
ML7	0.064	0.190	18 Int:107	DS	13.8	No	-	-	-	270	8	130	V-0	All	3

Multilayer rigid flex composite printed wiring boards, flammability only Recognition

SF1	-	-	-	DS	-	No	-	-	-	270	10	-	V-0	-	-
SF1<	-	-	-	DS	-	No	-	-	-	270	10	-	V-1	-	-
SF2	-	-	-	DS	-	No	-	-	-	270	10	-	V-0	-	-
SF2<	-	-	-	DS	-	No	-	-	-	270	10	-	V-0	-	-
SF7	-	-	-	DS	-	No	-	-	-	270	10	-	V-0	-	-
SF7<	-	-	-	DS	-	No	-	-	-	270	10	-	V-1	-	-

Multilayer Rigid Flex Composite, Flexible Materials Interconnect Constructions intended for use in flexible-rigid applications - Flammability Only Recognition.

ML-FR1	-	-	-	DS	-	No	-	-	-	288	10	-	V-0	-	-
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Multilayer Rigid Flex Composite, Flexible Materials Interconnect Constructions intended for use in flexible-rigid applications.

ML-FR (Note 1)	0.07	0.07	17 Int:68	DS	60	No	-	-	-	288	10	105	V-0	-	4
ML-FR(b) (Note 1)	0.07	0.09	17 Int:68	DS	60	No	-	-	-	288	10	105	V-0	-	-
ML-FR2	0.08	0.24	35 Int:35	SS	60	No	-	-	-	288	10	130	V-0	-	2
SF (Note 1)	0.09	0.09	17 Int:68	DS	60	No	-	-	-	288	20	130	V-0	All	3

Single layer flexible printed wiring boards															
FL	0.1	0.3	17.5	DS	61	No	-	-	-	250	30	105	V-0	-	-
Single Layer flexible printed wiring boards, flammability only Recognition															
FL1	-	-	-	DS	-	No	-	-	-	250	30	-	V-0	-	-
Single layer printed wiring boards															
5G	0.04	0.06	9	DS	50.8	No	-	-	-	288	20	130	V-1	All	*
5H	0.04	0.06	9	DS	50.8	No	-	-	-	288	20	130	V-0	All	*
D1	0.064	0.10	9	DS	127.0	No	-	-	-	288	20	125	V-0	All	*
D2	0.064	0.100	9	DS	50.0	No	-	-	-	288	20	130	V-0	All	*
D3 (ASP 1)	0.04	0.06	5	DS	90.0	Yes	Yes	260	6	-	-	130	V-0	All	*
D4	0.064	0.100	9	DS	127.0	No	-	-	-	288	20	130	V-0	All	3
D5	0.064	0.10	9	DS	127.0	No	-	-	-	288	20	130	V-0	All	*
D7 (ASP 1)	0.04	0.06	5	DS	90.0	Yes	Yes	260	4	-	-	120	V-0	All	3
DKL, EEL	0.064	0.19	18	DS	90.2	No	-	-	-	270	8	125	V-0	All	*
DKL2	0.18	0.53	18.3	DS	25.4	No	-	-	-	255	8	120	V-0	All	*
DKL3	0.083	0.25	18.3	DS	90.1	No	-	-	-	270	8	100	V-1	All	0
DKL4	0.064	0.10	9	DS	127.0	No	-	-	-	288	20	130	V-0	All	3
DKL6	0.064	0.19	18	DS	90.2	No	-	-	-	270	8	130	V-0	All	*
S6 (ASP 1)	0.04	0.06	5	DS	50.8	No	Yes	260	6	-	-	130	V-0	All	3
TF1	0.125	0.190	18	DS	89.9	No	-	-	-	288	10	150	V-0	All	0
TF2	0.125	0.190	18	DS	90.1	No	-	-	-	288	10	105	V-0	▲	0
TF3	0.16	0.22	18	DS	89.9	No	-	-	-	288	10	130	V-0	All	0

* - CTI marking is optional and may be marked on the printed wiring board.

ASP 1 - Assembly solder process evaluated to IPC-TM-650, 2.6.27 Thermal Stress Assembly Simulation

Note 1 - The copper thickness values shown are for the rigid section. For the flexible section, both internal and external copper are 35 mic only.

Marking: Company name or tradename "K", "KSG" or trademark  ,  ,  ,  or file number and type designation. May be followed by a suffix to denote factory identification or flammability classification..

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